

## N-Channel 40V(D-S) MOSFET

Product summary		
$V_{DS}$	40	V
$R_{DS(ON)}$ (at $V_{GS}=10V$ ) Typ.	2.2	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ ) Typ.	3.0	$m\Omega$
$I_D(T_c=25^\circ C)$	100	A

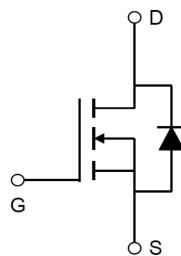
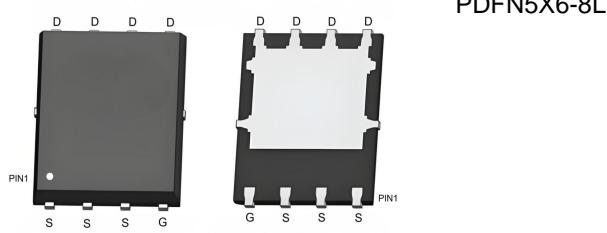
### Features

- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge

### Applications

- Load switching
- PWM Application
- Power Management

### Pin Configuration



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAP100N04A	PDFN5X6-8L	13 "	5000pcs

### Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_c=25^\circ C$	A
		$T_c=100^\circ C$	A
$I_{DM}$	Pulse Drain Current Tested <sup>A</sup>	400	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>B</sup>	225	mJ
$P_D$	Power Dissipation @ $T_c=25^\circ C$	61	W
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to +150	°C

### Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{eJC}$	Thermal Resistance-Junction to case max	2.0	°C/W

Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>Static Parameters</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	$\pm 100$	$\text{nA}$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance <sup>C</sup>	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	--	2.2	2.8	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=10\text{A}$	--	3.0	3.9	$\text{m}\Omega$
$V_{\text{SD}}$	Diode Forward Voltage	$I_{\text{S}}=30\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.2	V
<b>Dynamic Parameters <sup>D</sup></b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=20\text{V}$ $f=1\text{MHz}$	--	5500	--	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		--	415	--	$\text{pF}$
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	340	--	$\text{pF}$
$Q_g$	Total Gate Charge	$V_{\text{DS}}=20\text{V}, I_{\text{D}}=30\text{A}$ $V_{\text{GS}}=0 \text{ to } 10\text{V}$	--	59	--	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		--	13	--	$\text{nC}$
$Q_{\text{gd}}$	Gate-Drain Charge		--	15	--	$\text{nC}$
$t_{\text{D(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=20\text{V}$ $, R_{\text{G}}=3\Omega,$ $I_{\text{D}}=30\text{A},$ $V_{\text{GS}}=10\text{V}$	--	13	--	$\text{ns}$
$t_r$	Turn-on Rise Time		--	16	--	$\text{ns}$
$t_{\text{D(off)}}$	Turn-off Delay Time		--	39	--	$\text{ns}$
$t_f$	Turn-off Fall Time		--	15	--	$\text{ns}$

A. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

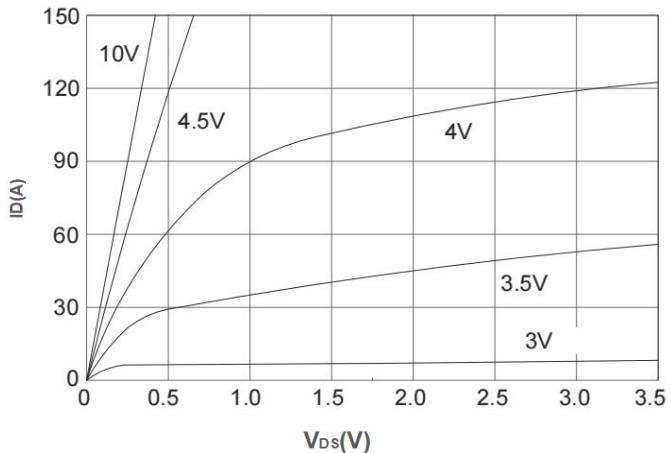
B. EAS condition: starting  $T_J=25^\circ\text{C}$ ,  $R_{\text{G}}=25\Omega$ ,  $V_{\text{DD}}=30\text{V}$ ,  $V_{\text{G}}=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $I_{\text{AS}}=30\text{A}$ .

C. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

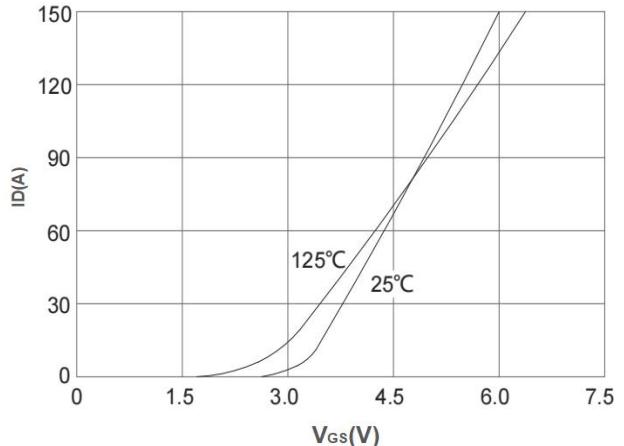
D. Guaranteed by design, not subject to production testing.

## Typical Characteristics

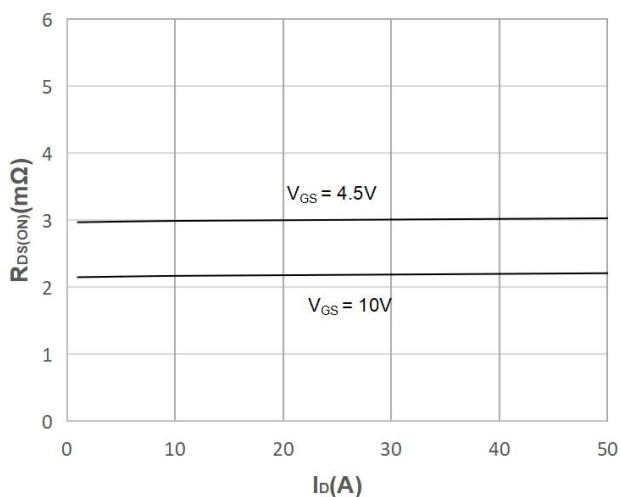
**Figure 1: Output Characteristics**



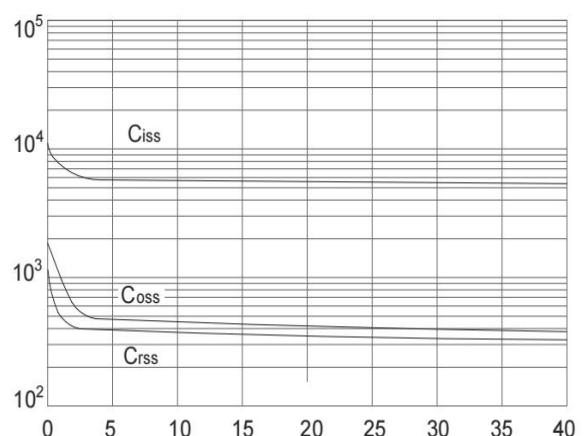
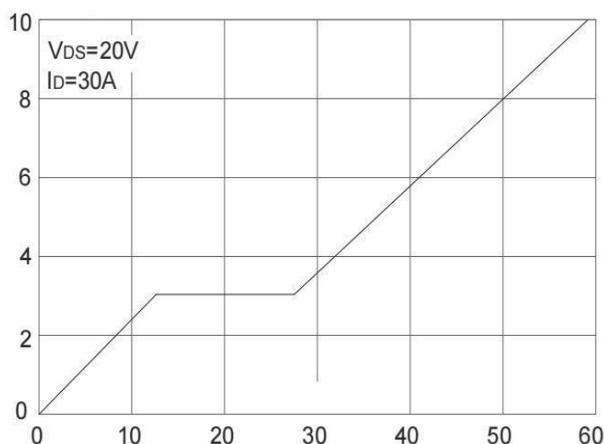
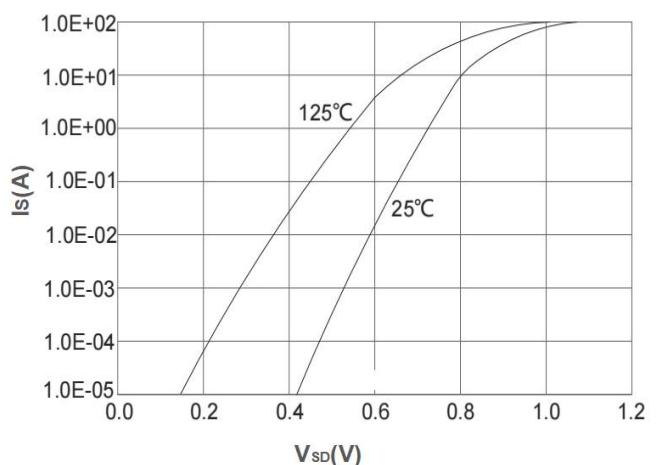
**Figure 2: Typical Transfer Characteristic**



**Figure 3: On-resistance vs. Drain Current**

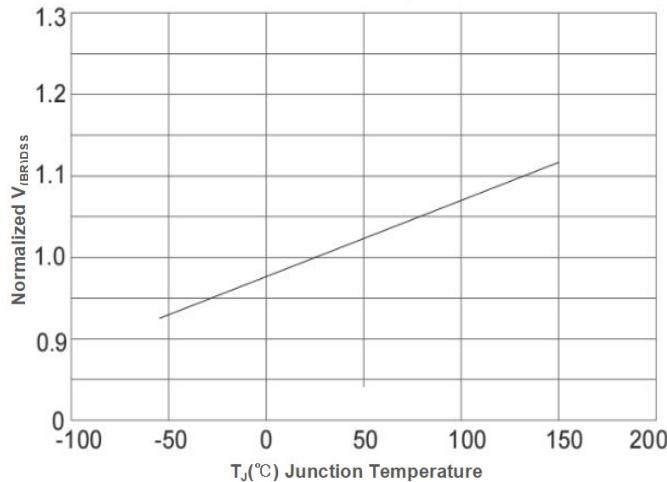


**Figure 4: Body Diode Characteristics**

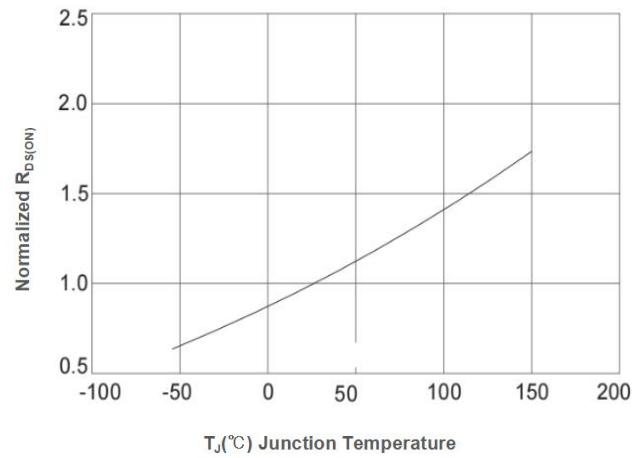


## Typical Characteristics

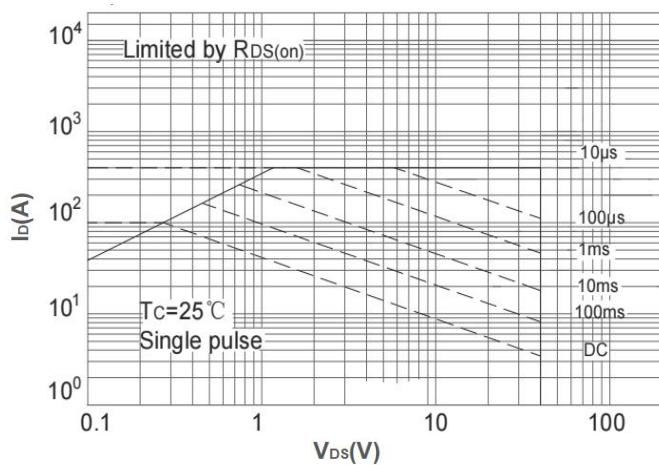
**Figure 7: Normalized Breakdown voltage vs. Junction Temperature**



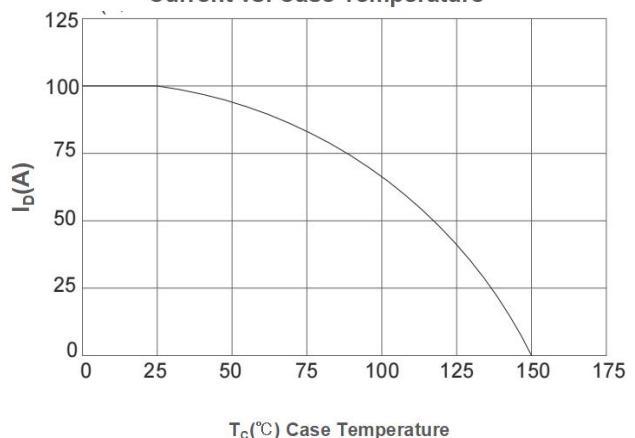
**Figure 8: Normalized on Resistance vs. Junction Temperature**



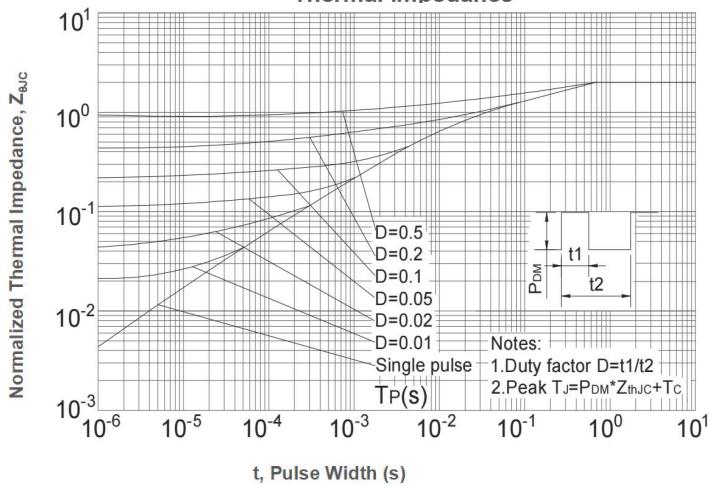
**Figure 9: Maximum Safe Operating Area**



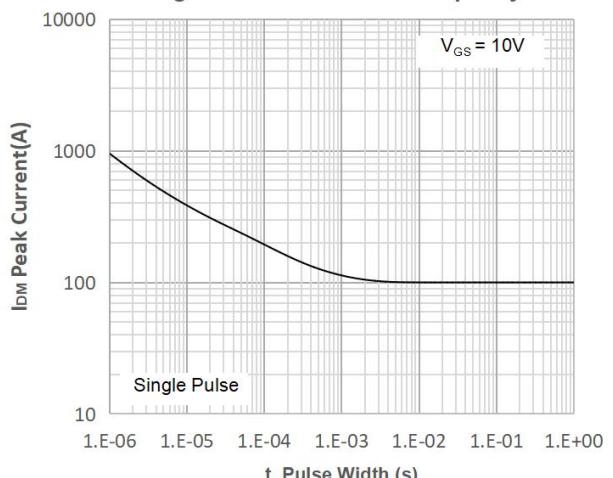
**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**



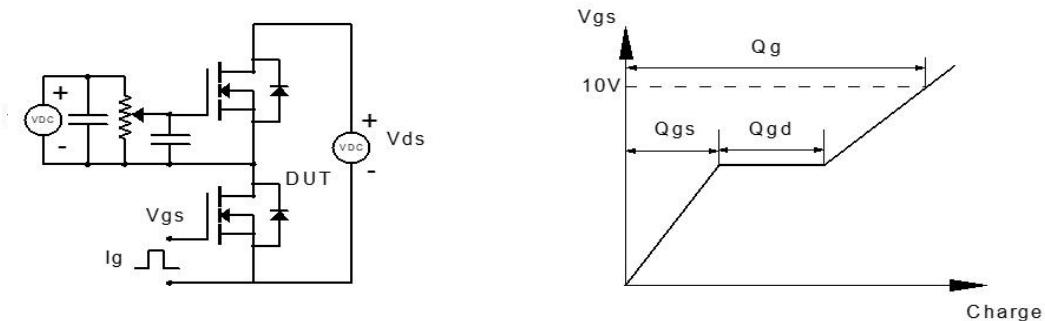
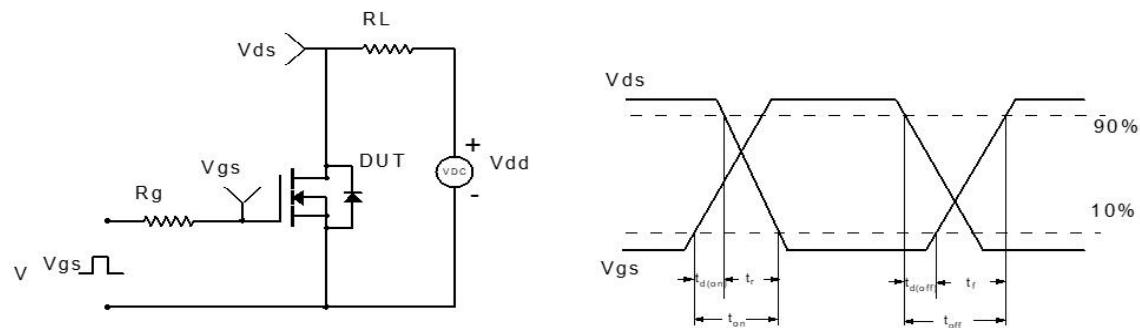
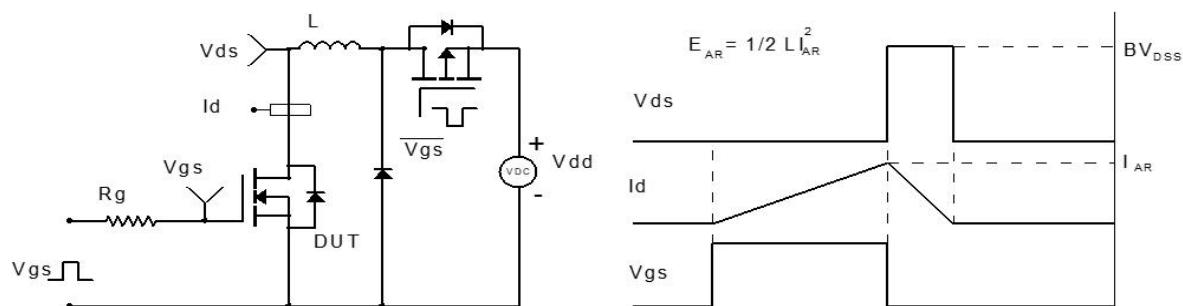
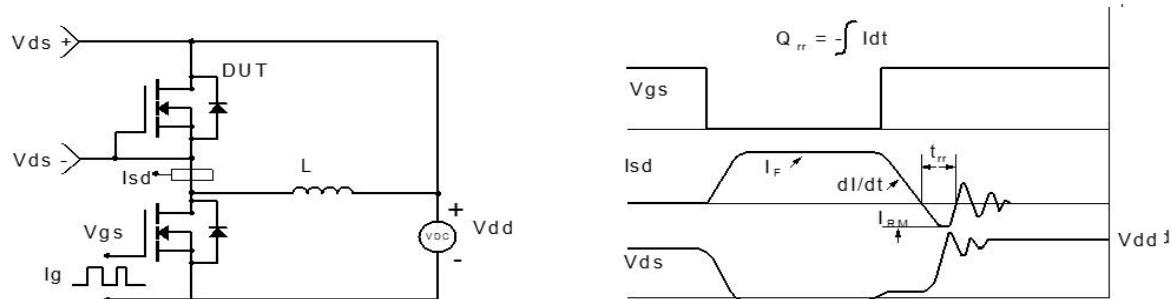
**Figure 11: Normalized Maximum Transient Thermal Impedance**

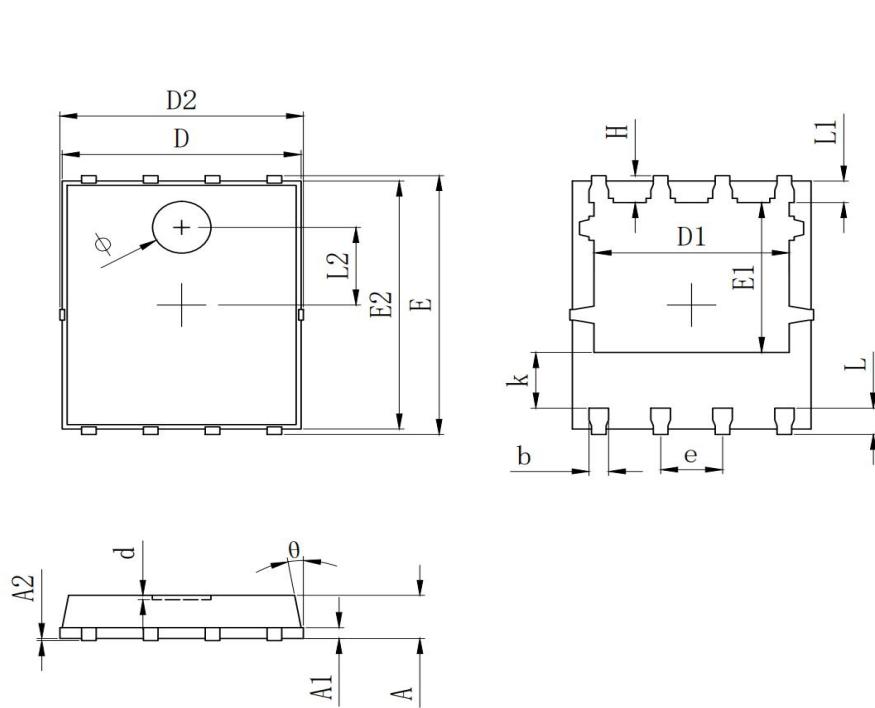


**Figure 12: Peak Current Capacity**



## Test Circuit


**Figure 1: Gate Charge Test Circuit & Waveform**

**Figure 2: Resistive Switching Test Circuit & Waveform**

**Figure 3: Unclamped Inductive Switching Test Circuit & Waveform**

**Figure 4: Diode Recovery Test Circuit & Waveform**

**PDFN5X6-8L Package Information (unit:mm)**


SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254 REF.		
A2	0~0.05		
D	4.824	4.900	4.976
D1	3.910	4.010	4.110
D2	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270 TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2	1.800 REF.		
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°
Φ	1.100	1.200	1.300
d			0.100